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In the Claims:

1. (Original) An electronic device (1)
  - 2 - with a base plate (2),
  - 3 - with an electronics housing (3) which is connected to
  - 4 the base plate (2), with at least one bond contact
  - 5 bearer (5),
  - 6 characterised in that the bond contact bearer (5) is
  - 7 supported on the base plate (2) by a supporting body (6) in
  - 8 such a manner that the supporting body (6) exerts a
  - 9 pretension force onto the bond contact bearer (5).
1. 2. (Original) An electronic device according to claim 1,  
2 characterised in that a projection of the supporting body  
3 (6) above the base plate (2) is greater than the distance  
4 between the bond contact bearer (5) and the base plate (2).

Claims 3 and 4 (Canceled).

1. 5. (Currently amended) A procedure for bonding [[an]] the  
2 electronic device (1) with the following procedural stages:  
3 according to claim 1, comprising the steps:
  - 4 — provision of a
  - 5 — providing the base plate (2),
  - 6 — connection of an
  - 7 — connecting the electronics housing (3) via [[a]] the
  - 8 — supporting body (6) with the base plate (2) in such a

9 manner that the supporting body (6) exerts [[a]] the  
10 pretension force onto the bond contact bearer (5), and  
11 ~~creation of~~

12 creating a bond connection between the bond contact  
13 bearer (5) of the electronics housing (3) and an additional  
14 bond contact bearer.

1 6. (Previously presented) An electronic device according to  
2 claim 1, characterized in that the supporting body (6)  
3 represents a separate component from the base plate (2),  
4 which is mechanically connected to the electronics housing  
5 (3).

1 7. (Previously presented) An electronic device according to  
2 claim 1, characterized in that the supporting body (6) is  
3 designed as a projecting ring or as a plurality of  
4 projecting individual segments.

[RESPONSE CONTINUES ON NEXT PAGE]